

### AMPMODU | AMPMODU System 50

TE Internal #: 104074-3

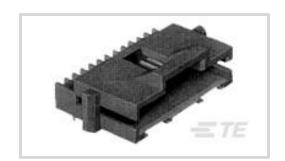
PCB Mount Header, Right Angle, Board-to-Board, 15 Position, 1.27 mm [.05 in] Centerline, Fully Shrouded, Gold (Au), AMPMODU

System 50

View on TE.com >



Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Type: PCB Mount Header

PCB Mount Orientation: Right Angle
Connector System: Board-to-Board

Number of Positions: 15

Number of Rows: 1

#### **Features**

#### **Product Type Features**

PCB Connector Type	PCB Mount Header
Connector System	Board-to-Board
Header Type	Fully Shrouded
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Connector Product Type	Connector Assembly

### **Configuration Features**

Connector Contact Load Condition	Fully Loaded
Board-to-Board Configuration	Perpendicular
PCB Mount Orientation	Right Angle
Number of Positions	15
Number of Rows	1

### **Electrical Characteristics**

Operating Voltage	30 VAC
Insulation Resistance	5000 MΩ
Dielectric Withstanding Voltage (Max)	500 VAC

### **Body Features**

PCB Retention Feature Plating Material	Tin-Lead over Nickel	
--	----------------------	--



Connector Profile	Standard
Primary Product Color	Black
Contact Features	
Contact Underplating Material	Nickel
PCB Contact Termination Area Plating Material Finish	Matte
Contact Mating Area Plating Material Thickness	.76 μm[30 μin]
Mating Square Post Dimension	.38 mm[.015 in]
PCB Contact Termination Area Plating Material Thickness	3.81 – 6.35 μm[150 – 250 μin]
Contact Shape & Form	Rectangular
Contact Base Material	Copper Alloy
PCB Contact Termination Area Plating Material	Tin-Lead
Contact Mating Area Plating Material	Gold (Au)
Contact Type	Pin
Contact Current Rating (Max)	3.6 A
Termination Features	
Termination Post & Tail Diameter	.38 mm[.015 in]
Termination Post & Tail Length	2.54 mm[.1 in]
Termination Method to PCB	Through Hole - Solder
Mechanical Attachment	
Mating Retention Type	Latching
Mating Retention	With
Mating Alignment Type	Polarization
PCB Mount Retention Type	Hold-Down Post
PCB Mount Retention	With
PCB Mount Alignment	Without
Connector Mounting Type	Board Mount
Mating Alignment	With
Housing Features	
Housing Material	LCP
Centerline (Pitch)	1.27 mm[.05 in]
Dimensions	
PCB Thickness (Recommended)	1.57 mm[.062 in]



### **Usage Conditions**

Housing Temperature Rating	High
Operating Temperature Range	-65 – 105 °C[-85 – 221 °F]
Operation/Application	
Solder Process Feature	Board Standoff
Circuit Application	Signal
Industry Standards	
Compatible With Agency/Standards Products	CSA, UL
UL Rating	Recognized
Compatible With Approved Standards Products	CSA LR7189, UL E28476
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Quantity	20
Packaging Method	Box, Tube

0

## **Product Compliance**

Position Locations Omitted

Other

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Not Compliant
EU ELV Directive 2000/53/EC	Compliant with Exemptions
China RoHS 2 Directive MIIT Order No 32, 2016	Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2025 (247) Candidate List Declared Against: JAN 2025 (247) SVHC > Threshold: Pb (13% in 4690971273) Article Safe Usage Statements: Do not eat, drink or smoke when using this product. Wash thoroughly after handling. Recycle if possible and dispose of the article by following all applicable governmental regulations relevant to your geographic location.
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Wave solder capable to 260°C

Product Compliance Disclaimer



This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

## Compatible Parts

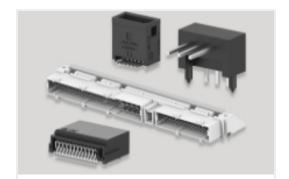




## Also in the Series | AMPMODU System 50



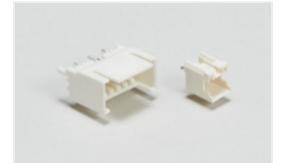
Board-to-Board Headers & Receptacles(685)



PCB Headers & Receptacles(685)



Rectangular Power Connectors(47)



Wire-to-Board Headers & Receptacles (47)

# Customers Also Bought





















### **Documents**

### **Product Drawings**

15 SYSTEM 50 HDR SRRA SHRD

English

### **CAD Files**

3D PDF

3D

**Customer View Model** 

ENG\_CVM\_CVM\_104074-3\_W.2d\_dxf.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_104074-3\_W.3d\_igs.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_104074-3\_W.3d\_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

### **Product Specifications**

**Application Specification** 

English